MOSFETs Silicon P-Channel MOS (U-MOSVI)

# TJ10S04M3L

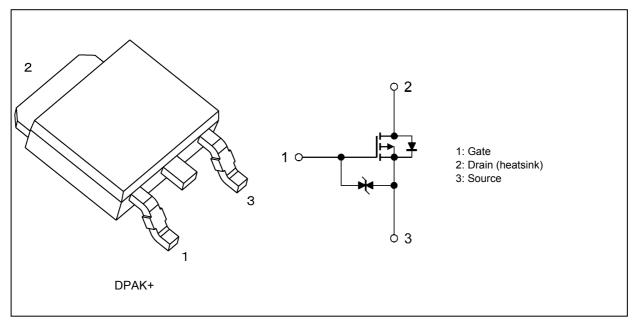
#### 1. Applications

- Automotive
- Motor Drivers
- DC-DC Converters
- Switching Voltage Regulators

#### 2. Features

- (1) AEC-Q101 qualified
- (2) Low drain-source on-resistance:  $R_{DS(ON)} = 33.8 \text{ m}\Omega$  (typ.) (V<sub>GS</sub> = -10 V)
- (3) Low leakage current:  $I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -40 \ V)$
- (4) Enhancement mode:  $V_{th}$  = -2.0 to -3.0 V ( $V_{DS}$  = -10 V,  $I_D$  = -1 mA)

#### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			V <sub>DSS</sub>	-40	V
Gate-source voltage			V <sub>GSS</sub>	-20/+10	1
Drain current (DC)		(Note 1)	Ι <sub>D</sub>	-10	Α
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	-20	
Power dissipation	(T <sub>c</sub> = 25°C)		PD	27	W
Single-pulse avalanche energy		(Note 2)	E <sub>AS</sub>	23	mJ
Avalanche current			I <sub>AR</sub>	-10	A
Channel temperature		(Note 3)	T <sub>ch</sub>	175	°C
Storage temperature		(Note 3)	T <sub>stg</sub>	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance	R <sub>th(ch-c)</sub>	5.4	°C/W

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2: V\_{DD} = -25 V, T\_{ch} = 25°C (initial), L = 243  $\mu H,$  R\_G = 25  $\Omega,$  I\_{AR} = -10 A

Note 3: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

### 6. Electrical Characteristics

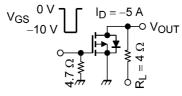
### 6.1. Static Characteristics (Ta = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = -16/+10 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = -40 V, V <sub>GS</sub> = 0 V	—	—	-10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 0 V	-40	_	_	V
Drain-source breakdown voltage (Note 4)	V <sub>(BR)DSX</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 10 V	-30	_	_	
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1 mA	-2.0	_	-3.0	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -6 V, I <sub>D</sub> = -5 A	—	42	62	mΩ
		V <sub>GS</sub> = -10 V, I <sub>D</sub> = -5 A	—	33.8	44	

Note 4: If a forward bias is applied between gate and source, this device enters V<sub>(BR)DSX</sub> mode. Note that the drainsource breakdown voltage is lowered in this mode.

### 6.2. Dynamic Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	930	_	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	90	_	
Output capacitance	C <sub>oss</sub>		_	140	_	
Switching time (rise time)	tr	See Figure 6.2.1.	_	7	_	ns
Switching time (turn-on time)	t <sub>on</sub>			15	_	
Switching time (fall time)	t <sub>f</sub>			40	_	
Switching time (turn-off time)	t <sub>off</sub>		_	145	_	



 $V_{DD} \approx -20 \ V$ 

Duty  $\leq$  1%,  $t_W =$  10  $\mu s$ 

Fig. 6.2.1 Switching Time Test Circuit

#### 6.3. Gate Charge Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx -32$ V, $V_{GS}$ = -10 V, $I_D$ = -10 A	—	19	—	nC
Gate-source charge	Q <sub>gs</sub>		_	13.5	_	
Gate-drain charge	Q <sub>gd</sub>			5.5	_	

#### 6.4. Source-Drain Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (DC)	(Note 5)	I <sub>DR</sub>	—	_	_	-10	А
Reverse drain current (pulsed)	(Note 5)	I <sub>DRP</sub>	—	_	_	-20	
Diode forward voltage		$V_{DSF}$	I <sub>DR</sub> = -10 A, V <sub>GS</sub> = 0 V	_	_	1.2	V
Reverse recovery time		t <sub>rr</sub>	I <sub>DR</sub> = -10 A, V <sub>GS</sub> = 0 V	_	28	_	ns
Reverse recovery charge		Q <sub>rr</sub>	dl <sub>DR</sub> /dt = 50 A/µs		11	_	nC

Note 5: Ensure that the channel temperature does not exceed 175°C.

### 7. Marking (Note)

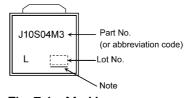
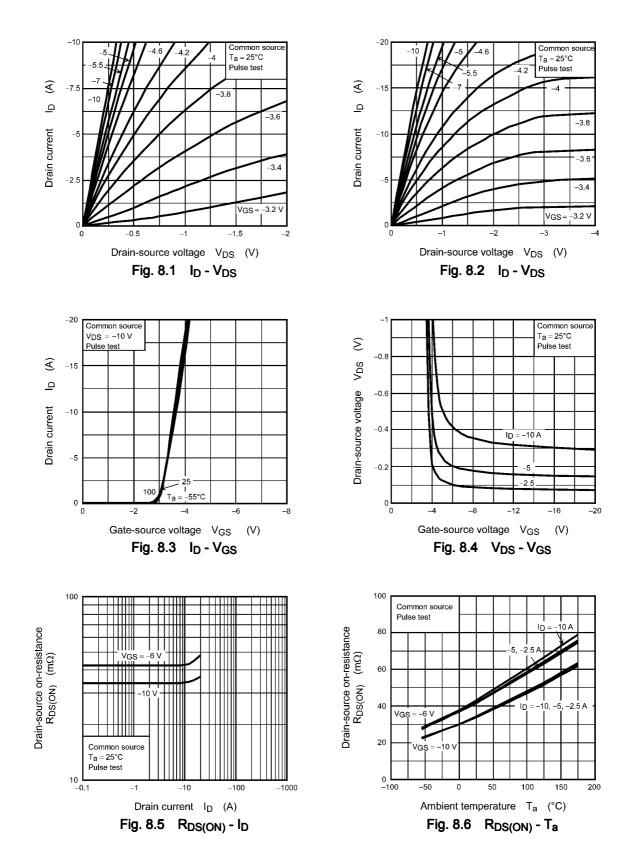
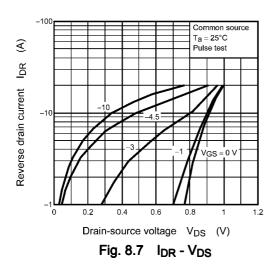


Fig. 7.1 Marking

Note: A line under a Lot No. identifies the indication of product Labels. Not underlined: [[Pb]]/INCLUDES > MCV Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]] Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

#### 8. Characteristics Curves (Note)





Common source

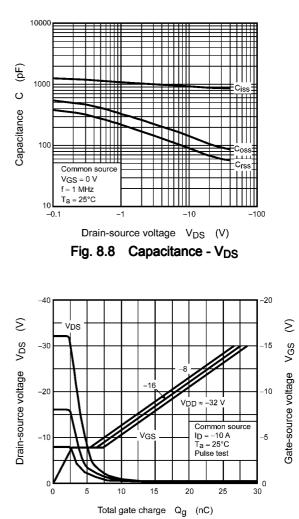


Fig. 8.10 Dynamic Input/Output Characteristics

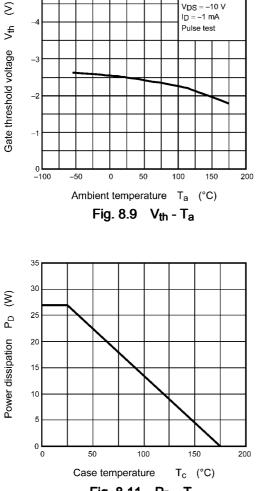
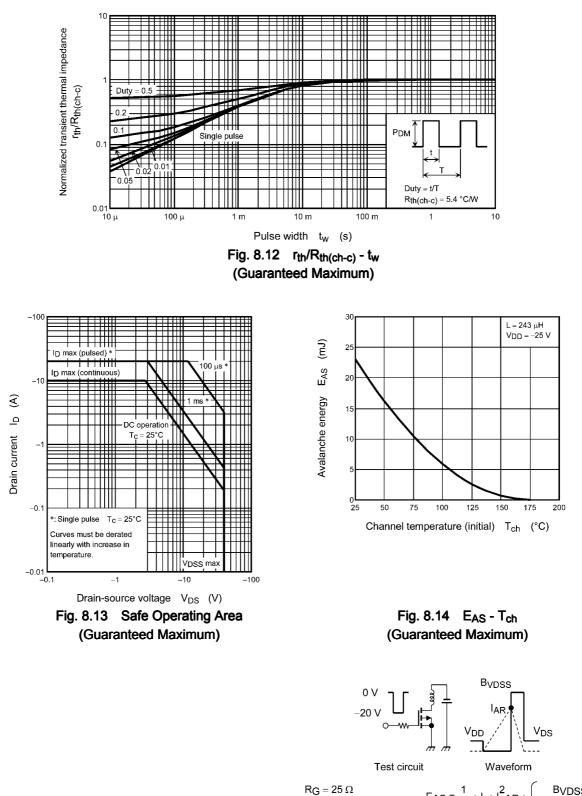
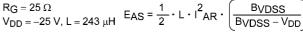


Fig. 8.11 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)





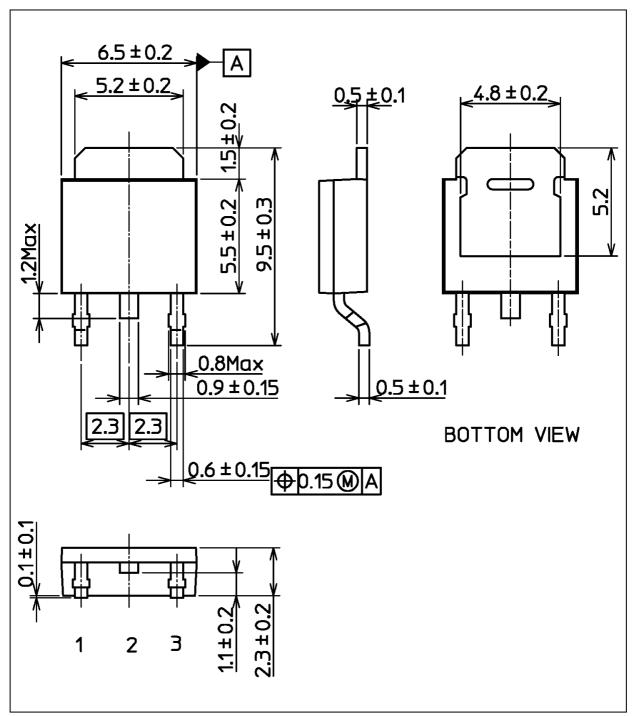




Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

### Package Dimensions

Unit: mm



Weight: 0.36 g (typ.)

	Package Name(s)
TOSHIBA: 2-7M1A	
Nickname: DPAK+	

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